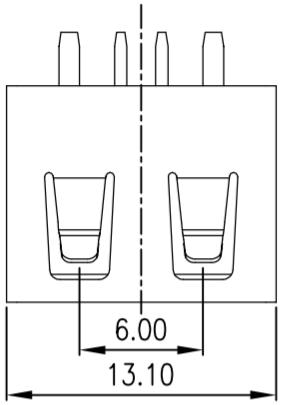
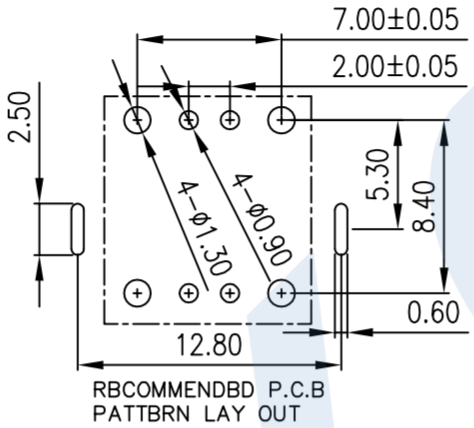
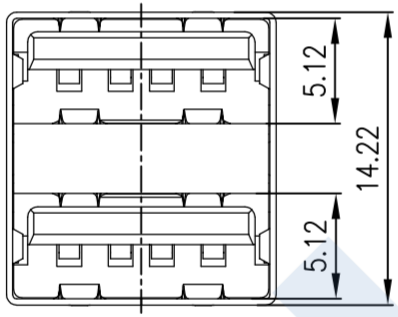
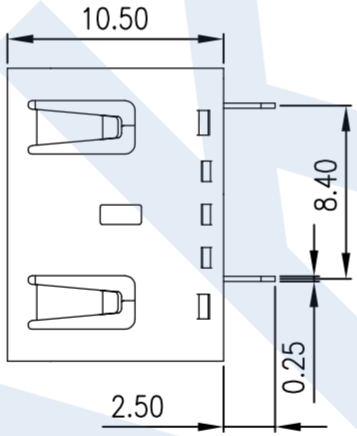
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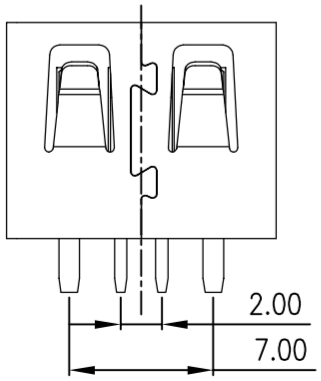
REV.	ECN NO.	DESCRIPTION	DRWN	APPD.	DATE.











Note:

1.Material:

1.1,Housing: High temperature thermoplastic with/black G/F,UL94v-0

1.2,Contact: copper alloy,t=0.25mm

1.3,Shell: copper/Ferroalloy alloy,t=0.30mm

2.Specification:

2.1,Current rating:3.0A Max.

2.2,Dielectric withstanding voltage: 100 V(ac) for 1 min.

2.3,Contact resistance: 30 mΩ Max.

2.4,Insulation resistance: 100 MΩ Min.

2.5,Total mating force: 3.57 Kgf Max.

2.6,Total unmating force: 1.0 Kgf Min.

3.Finish:

3.1,Contact: Piated Golg in Mating Area: Tin On Solder Talls

Shell: Nickel Plating

4.Environmental:

4.1,Temperature range: -55°C~85°C

UNITS	SCALE
MM	1:1

GENERAL TOLERANCE

X.	±0.30
X.X	±0.20
X.XX	±0.10
X.°	±3°
X.X°	±2°

GKKG

DR. Lila	TITLE: USB AF 10.5双层180度无脚无卷边(大电流)			
CHK. Loran		DWG NO: USB-U1026J		
APPD. LIGUIYUAN	DATE: 2011.06.28	P	PART NO:	SIZE A4